



ETJ

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Keith E. FOGEL et al. CONFIRM. NO.: 6557
SERIAL NO.: 10/815,103 ART UNIT: 2826
FILED: 03/31/2004 EXAMINER: L. ANDUJAR
TITLE: INTERCONNECTIONS FOR FLIP-CHIP USING LEAD-FREE
SOLDERS AND HAVING REACTION BARRIER LAYERS
ATTORNEY DOCKET NO.: YOR920030190US1

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

Responsive to the Office Action of October 31, 2006,
please reconsider this application in view of the
following:

Listing of and Amendments to Claims, Page 2

Remarks Page 7

Certificate of Mailing

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first
class mail in an envelope addressed to: Commissioner for
Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

April 30, 2007
Date

David Allen
Name of Person Making Deposit